

MW-G

- MW-G 铜箔系适用于Hi-Tg及无卤素基板之符合新一代环保要求之电解铜箔。
MW-G copper foil comply with environment regulation is especially suitable for Hi-Tg and Halogen Free prepregs.
- 具优良的抗撕强度/极佳的耐热性/优越的蚀刻性。
Good bonding strength./ Excellent heat resistance./ Good etchability.
- 9 μm 之薄铜箔稳定的量产能力, 可充分供应客户需求。
Our plant has stable capacity for 9 μm thin foil to fulfill customer requirements.

用途/Application

- 适用于多层印刷电路板(HDI)
/High Density Interconnect(HDI)
- 封装基板(薄铜)
/Semiconductor Package(thin copper foil)

结构/Composition



生产地点/Production Site

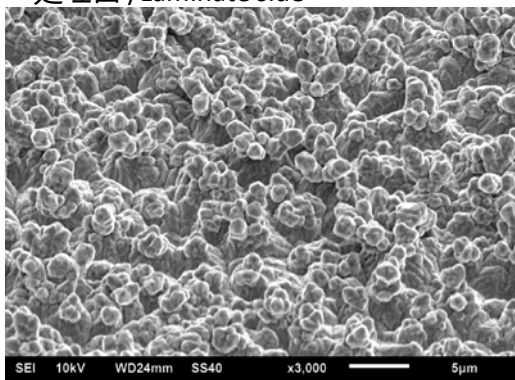
- 台湾 / Taiwan
- 马来西亚 / Malaysia

特性代表值/Representative data

	μm	Rz (μm)	Tensile Strength (N/mm ²)	Elongation (%)	Peel Strength (kg/cm)
MW-G	9	3.8	370	4	0.9
	12	4.2	370	6	1.2

※上述表列为代表性数据非保证值。
This is representative data, not guarantee.

处理面 / Laminate side



阻剂面 / Resist side

